Advanced Packaging Update:
Market and Technology Trends

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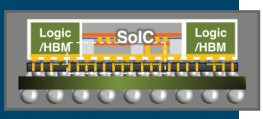

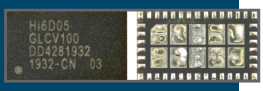

This issue of the Advanced Packaging Update features special coverage of large area panel fan-out wafer level packaging (FO-WLP) developments. The panel market is divided into high-density RDL (≤2µm L/S with multiple RDLs) versus low-density (>5µm L/S with ≤3 RDLs). Panel activities at major organizations are discussed and a market forecast for low-density panels is included. High-performance packaging options including silicon interposers and alternatives such as fan-out on substrate are presented. A special section examines developments in electro-magnetic interference (EMI) shielding. Huawei's new 5G smartphone is examined. Outsourced semiconductor assembly and test (OSAT) financials are analyzed.

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TechSearch INTERNATIONAL
4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com